



钜地半导体
Tudi Semiconductor

Product Specification

TUDI-MC3487

Quad differential line driver

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**semiconductor device
manufacturer**

- Design
- research and development
- production
- and sales

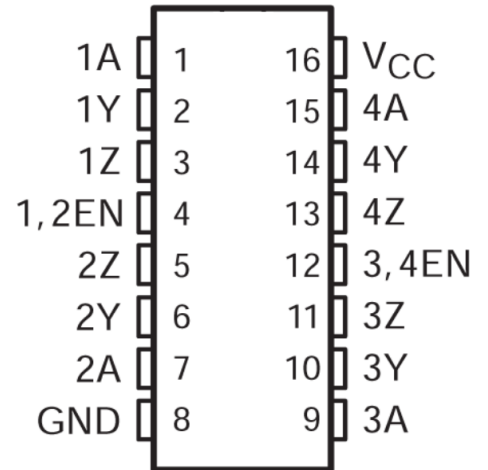


Features

- Meets or exceeds the requirements of ANSI TIA/EIA -422-B and ITU Recommendation V.11
- Tri-state TTL output
- Fast transition time
- High impedance input
- 5V single power supply
- Power-up and power-down protection

Applications

- Factory automation
- ATMs and banknote counters
- Smart grids
- AC and servo motor drives



MC3487

Description

The MC3487 provides four independent differential line drivers designed to comply with the ANSI TIA/EIA-422-B and Recommendation V.11 specifications. Each driver has a buffered TTL-compatible input to reduce current and further reduce loading.

When the appropriate output enable is at a logic low level the driver output uses a tri-state circuit to provide a high-impedance state on any pair of differential outputs. If the output enable is low, the internal circuitry is in high-impedance state at the differential outputs during power-up and power-down transitions.

The MC3487 is designed to be used with the MC346 quad line receiver to achieve superior performance. The device is housed in a 16-pin Dual-In-Line package and operates from a single 5V power supply



Pin Configuration and Functions

Pin Functions

PIN		TYPE ⁽¹⁾	DESCRIPTION
NAME	NO.		
1A	1	I	Single Ended Data Input for Channel 1
1Y	2	O	Non-Inverting Output for Differential Driver on Channel 1
1Z	3	O	Inverting Output of Differential Driver on Channel 1
1,2EN	4	I	Enable Input for Channels 1 and 2
2Z	5	O	Inverting Output of Differential Driver on Channel 2
2Y	6	O	Non-Inverting Output for Differential Driver on Channel 2
2A	7	I	Single Ended Data Input for Channel 2
GND	8	GND	Device Ground
3A	9	I	Single Ended Data Input for Channel 3
3Y	10	O	Non-Inverting Output for Differential Driver on Channel 3
3Z	11	O	Inverting Output of Differential Driver on Channel 3
3,4EN	12	I	Enable Input for Channels 3 and 4
4Z	13	O	Inverting Output of Differential Driver on Channel 4
4Y	14	O	Non-Inverting Output for Differential Driver on Channel 4
4A	15	I	Single Ended Data Input for Channel 4
Vcc	16	P	5V Power Supply Positive Terminal Connection

(1) Signal Types: I = Input, O = Output, I/O = Input or Output, P = Power, GND = Ground.



Specifications

Absolute Maximum Ratings

over operating free-air temperature range (unless otherwise noted)⁽¹⁾

		MIN	MAX	UNIT
V_{cc} (see ⁽²⁾)	Supply voltage		7	V
V_I	Input voltage		5.5	V
V_o	Output voltage		7	V
T_J	Operating virtual junction temperature		150	
T_{stg}	Storage temperature range	-65	150	

(1) Stresses beyond those listed under “ absolute maximum ratings ” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “ recommended operating conditions ” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

(2) All voltage values, except differential output voltage, V_{OD} , are with respect to the network ground terminal.

Recommended Operating Conditions

		MIN	NOM	MAX	UNIT
V_{cc}	Supply voltage	4.75	5	5.25	V
V_{IH}	High-level input voltage	2			V
V_{IL}	Low-level input voltage			0.8	V
T_A	Operating free-air temperature	0		70	



Thermal Information

THERMAL METRIC ⁽¹⁾		D (SOIC)	N(PDIP)	NS (SOP)	UNIT
		16-PINS			
R θ _{JA}	Junction-to-ambient thermal resistance	84.6	60.6	88.5	/W
R θ _{JC(top)}	Junction-to-case (top)thermal resistance	43.5	48.1	46.2	/W
R θ _{JB}	Junction-to-board thermal resistance	43.2	40.6	50.7	/W
ψ _{JT}	Junction-to-top characterization parameter	10.4	27.5	13.5	/W
ψ _{JB}	Junction-to-board characterization parameter	42.8	40.3	50.3	/W
R θ _{JC(bot)}	Junction-to-case (bottom)thermal resistance	N/A	N/A	N/A	/W

(1) For more information about traditional and new thermal metrics, see the Semiconductor and IC package thermal metrics application report.

Device Functional Modes

Function Table (Each Driver)

INPUT	OUTPUT ENABLE ⁽¹⁾	OUTPUTS	
		Y	Z
H	H	H	L
L	H	L	H
X	L	Z	Z

(1) H = TTL high level, L = TTL low level, X = irrelevant, Z = High impedance



Electrical Characteristics

over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)

PARAMETER		TEST CONDITIONS			MIN	MAX	UNIT
V _{IK}	Input clamp voltage	I _I =-18 mA				-1.5	V
V _{oH}	High-level output voltage	V _{IL} =0.8V,	V _{IH} =2V,	I _{oH} =-20 mA	2.5		V
V _{oL}	Low-level output voltage	V _L =0.8V,	V _{IH} =2V,	I _{oL} =48mA		0.5	V
IV _{oo} I	Differential output voltage	R _L =100 Q	See 图 1		2		
IV _{oo} I	Change in magnitude of differentialoutput voltage ⁽¹⁾	R _L =1000	See 图 1			± 0.4	V
Voc	Common-mode output voltage ⁽²⁾	R _L =1000	See 图 1			3	V
IV _{oc} I	Change in magnitude of common-mode output voltage ⁽¹⁾	R _L =1000	See 图 1			± 0.4	V
I _o	Output current with power off	V _{cc} =0	V _o =6V			100	μA
			V _o =-0.25V			-100	
I _{oz}	High-impedance-state outputcurrent	Output enables at 0.8V	V _o =2.7V			100	μA
			V _o =0.5V			-100	
I _I	Input current at maximum inputvoltage	V ₁ =5.5V				100	μA
I _H	High-level input current	V ₁ =2.7V				50	μA
I _I	Low-level input current	V ₁ =0.5V				-400	μA
I _{os}	Short-circuit output current ⁽³⁾	V ₁ =2V			-40	-140	mA
I _{cc}	Supply current (alldrivers)	Outputs disabled				105	mA
		Outputs enabled, No load				85	

(1) $\Delta |V_{OD}|$ and $\Delta |V_{OC}|$ are the changes in magnitude of V_{OD} and V_{OC} , respectively, that occur when the input is changed from a high level to a low level.

(2) In ANSI Standard TIA/EIA-422-B, V_{OC} , which is the average of the two output voltages with respect to ground, is called output offset voltage, V_{OS} .

(3) Only one output at a time should be shorted, and duration of the short circuit should not exceed one second.

Switching Characteristics

over recommended operating free-air temperature range, $V_{CC} = 5\text{ V}$

PARAMETER		TEST	CONDITIONS	MIN	MAX	UNIT
t_{PLH}	Propagation delay time, low-to high-level output	$C_L = 15\text{ pF}$	See 图 2		20	ns
t_{PHL}	Propagation delay time, high-to low-level output				20	
t_{sk}	Skew time	$C_L = 15\text{ pF}$	See 图 2		6	ns
t_{OD}	Differential-output transition time	$C_L = 15\text{ pF}$	See 图 3		20	ns
t_{pZH}	Output enable time to high level	$C_L = 50\text{ pF}$	See 图 4		30	ns
t_{pZL}	Output enable time to low level				30	
t_{PHZ}	Output disable time from high level	$C_L = 50\text{ pF}$	See 图 4		25	ns
t_{PLZ}	Output disable time from low level				30	

Parameter Measurement Information

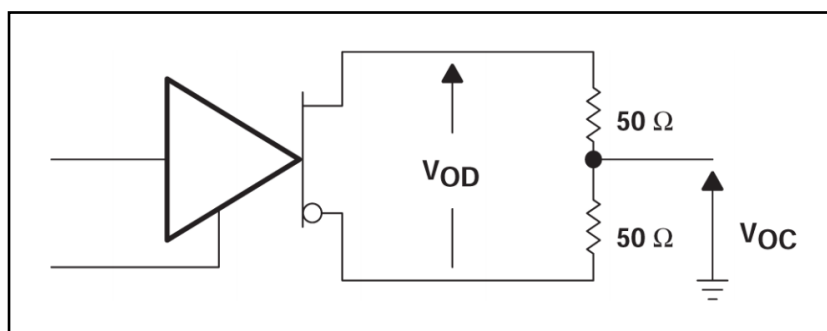


图 1. Differential and Common-Mode Output Voltages

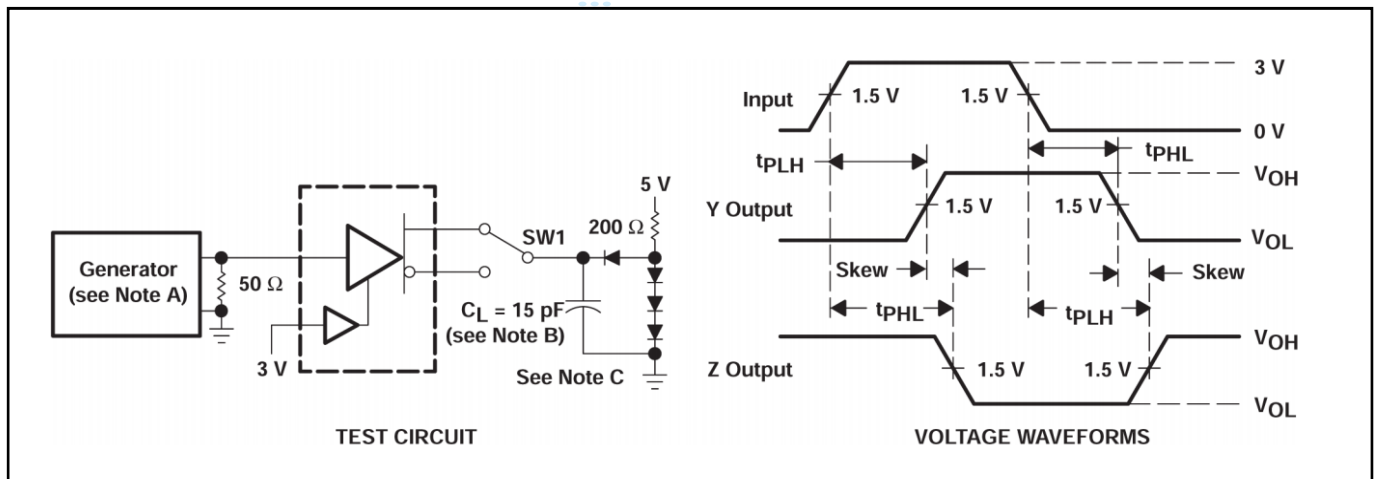


图 2. Test Circuit and Voltage Waveforms

- A. The input pulse is supplied by a generator having the following characteristics: $t_r \leq 5 \text{ ns}$, $t_f \leq 5 \text{ ns}$, $\text{PRR} \leq 1 \text{ MHz}$, duty cycle = 50%, $Z_o = 50 \Omega$.
 B. C_L includes probe and stray capacitance.
 C. All diodes are 1N916 or 1N3064.

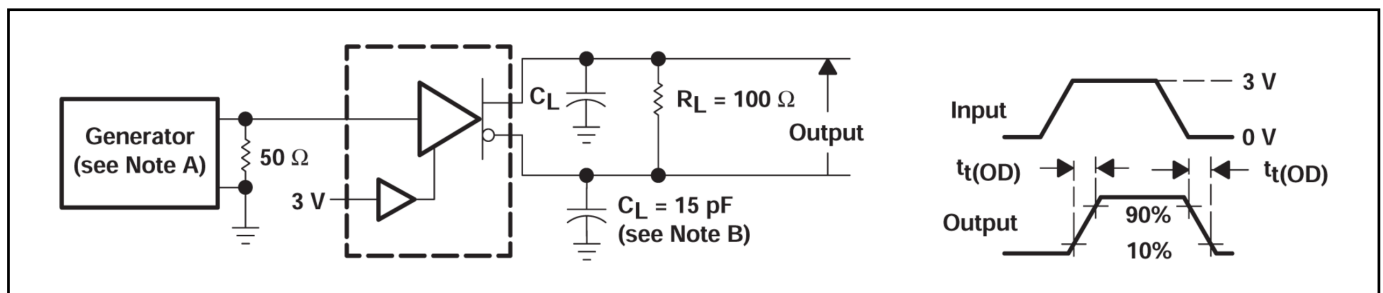
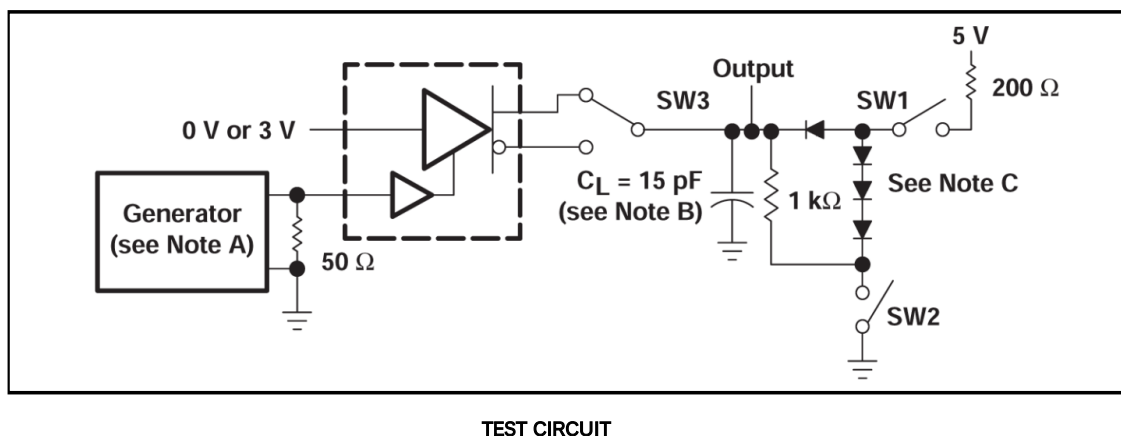
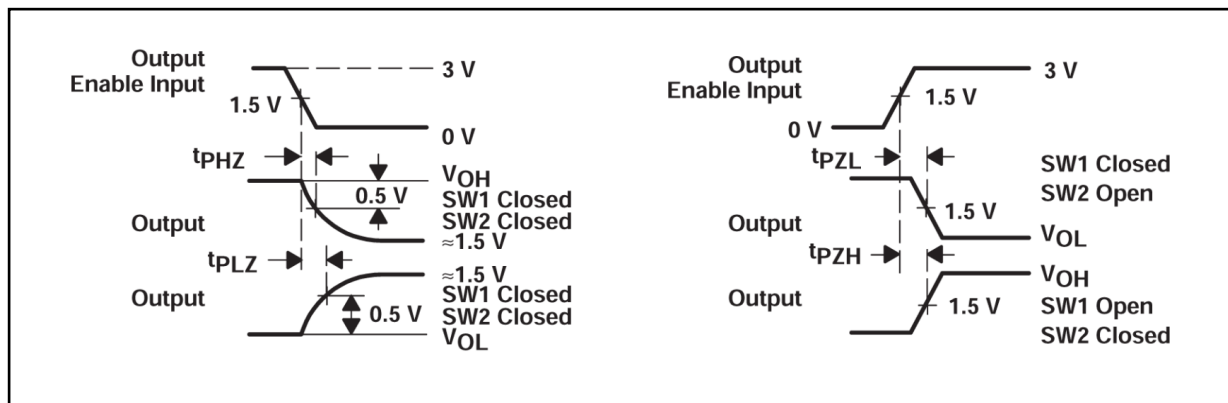


图 3. Test Circuit and Voltage Waveforms

- A. The input pulse is supplied by a generator having the following characteristics: $t_r \leq 5 \text{ ns}$, $t_f \leq 5 \text{ ns}$, $\text{PRR} \leq 1 \text{ MHz}$, duty cycle = 50%, $Z_o = 50 \Omega$.
 B. C_L includes probe and stray capacitance.



TEST CIRCUIT



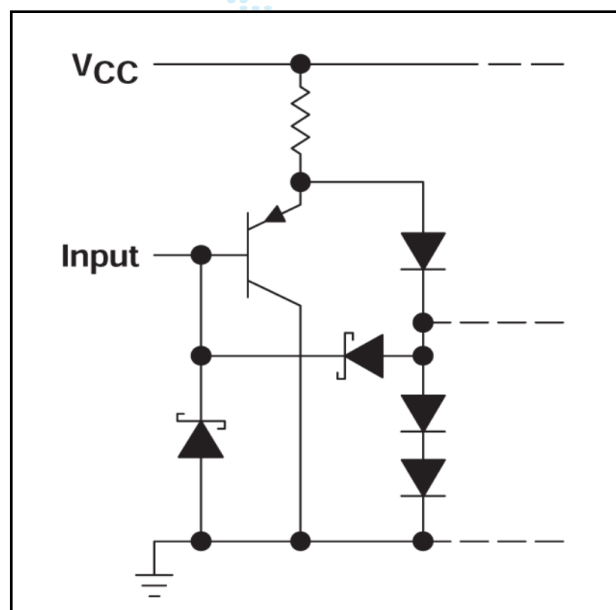
VOLTAGE WAVEFORMS

图 4. Driver Test Circuit and Voltage Waveforms

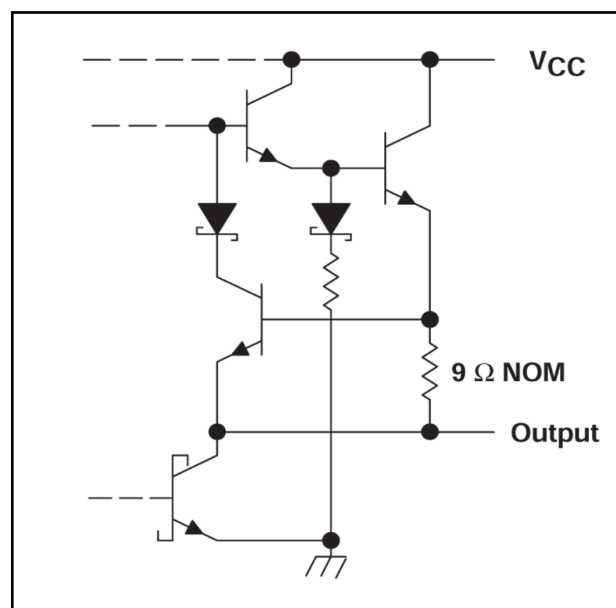
- A. The input pulse is supplied by a generator having the following characteristics: $t_r \leq 5 \text{ ns}$, $t_f \leq 5 \text{ ns}$, $\text{PRR} \leq 1 \text{ MHz}$, duty cycle = 50%, $Z_O = 50 \Omega$.
B. CL includes probe and stray capacitance.
C. All diodes are 1N916 or 1N3064.

Order information

Order Number	Package	Package Quantity	Marking On The park	Temperature
MC3487DR-TUDI	SOP16	Tape,Reel,2500	MC3487	0°C to 70°C
MC3487N-TUDI	DIP16	Tube,25,A box of 2000	MC3487N	



EQUIVALENT OF EACH INPUT

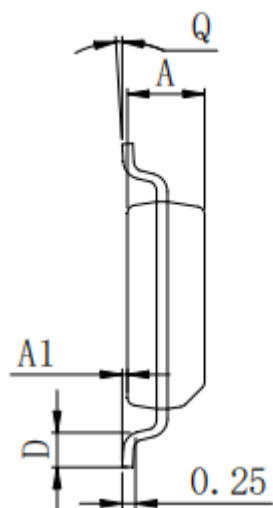
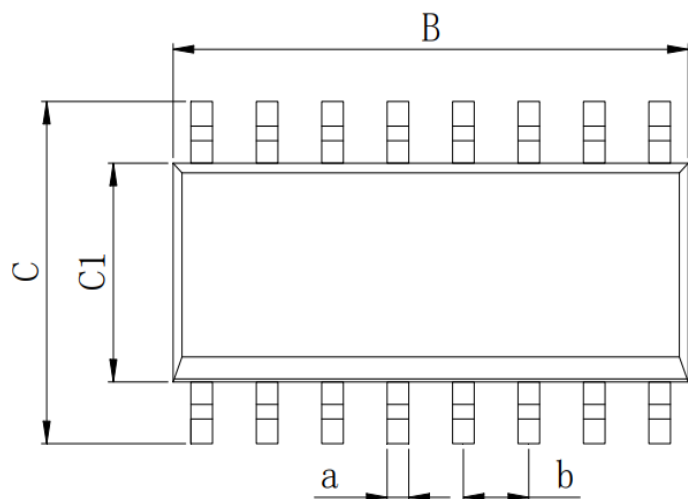


TYPICAL OF ALL OUTPUTS

图5 Schematics of Inputs and Outputs

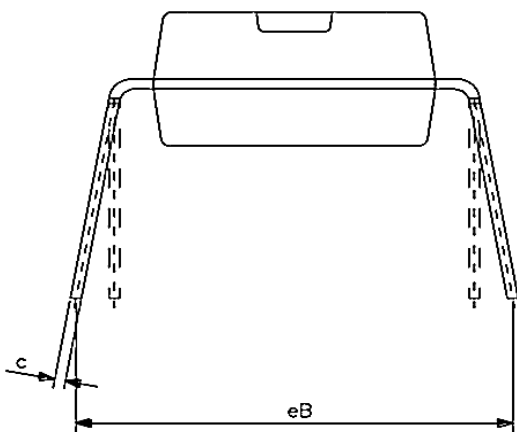
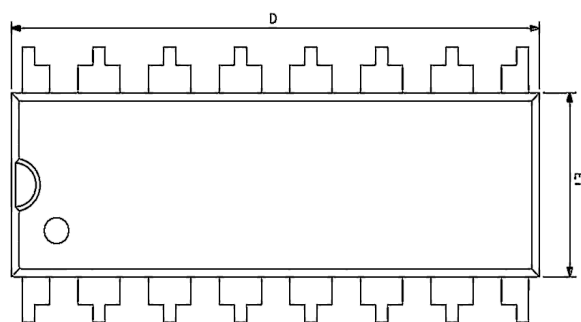
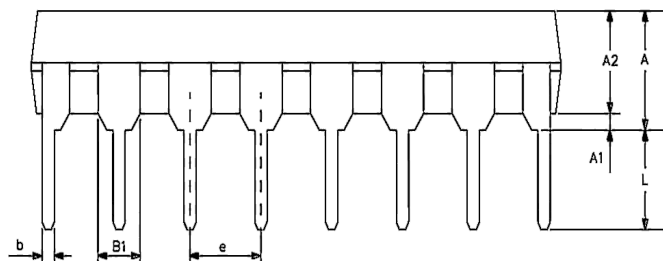


Package SOP16



SYMBOL	MIN./mm	MAX./mm
A	1.35	1.55
A1	0.05	0.2
B	9.80	10.00
C	5.80	6.20
C1	3.80	4.00
D	0.40	0.80
Q	0°	8°
a	0.35	0.45
b	1.27BSC	

Package DIP16



SIZE SYMBOL	MIN./mm	MAX./mm
A2	3.20	3.60
A1	0.51	—
A	3.60	5.33
L	3.00	3.60
b	0.36	0.56
B1	1.52	
D	18.80	19.94
E1	6.20	6.60
e	2.54	
C	0.20	0.36
eB	7.62	9.30
R	0.20TYP	
R1	0.30TYP	
θ	0°	8°
θ1	45°TYP	
02	12°TYP	
03	0°	8°
04	0°	10°



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